



Latest Advances and Applications of Infrared Thermography Non-destructive Testing (NDT): 2nd Edition

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Deadline for manuscript
submissions:

closed (10 August 2024)

Message from the Guest Editor

Dear Colleagues,

Infrared thermography has undergone a remarkable transformation over the last century, owing to the enormous progress in microsystem technologies of infrared detector design, electronics, and computer science. Currently, thermal imaging plays an essential role in research and development; safety and law enforcement; medicine; wildlife; energy efficiency; and a variety of different fields in the industry, such as condition monitoring, predictive maintenance, and non-destructive testing and evaluation. This Special Issue explores theoretical, numerical, and experimental advances in infrared thermography and its application in a variety of fields. We invite researchers to contribute original research, case studies, industrial and bio-medical applications, and review articles with a focus on the current state of the art.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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